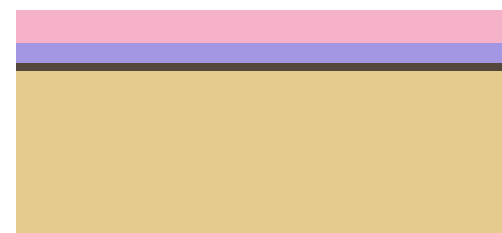




(a) Graphene CVD growth



(b) Hyflon spin coating



(c) Photoresist spin-coating



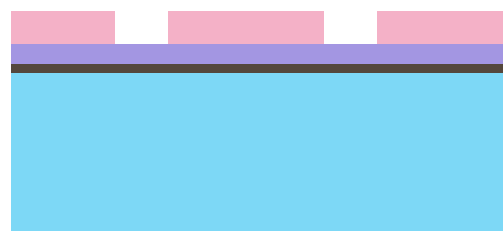
(d) Copper etching,
DI water rinsing



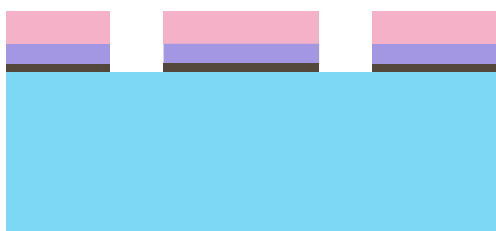
(e) Transfer onto LAO/STO,
soft-baking



(f) Photoresist removal,
2nd photoresist spin-coating



(g) Photolithography



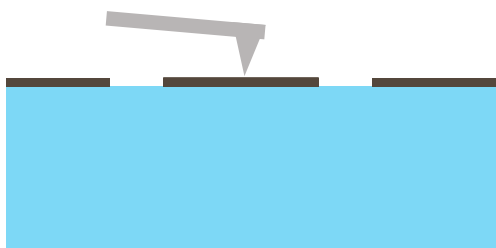
(h) Oxygen plasma etching



(i) Acetone rinsing



(j) FC-40 rinsing



(k) AFM cleaning

